



Gap Pad® VO Ultra Soft

July 2011

PRODUCT DESCRIPTION

Ultra Conformable, Thermally Conductive Material for Filling Air Gaps

FEATURES AND BENEFITS

- Thermal conductivity: 1.0 W/m-K
- · Highly conformable, low hardness
- · "Gel-like" modulus
- · Decreased strain
- · Puncture, shear and tear resistant
- · Electrically isolating



Gap Pad® VO Ultra Soft is recommended for applications that require a minimum amount of pressure on components. The viscoelastic nature of the material also gives excellent low-stress vibration dampening and shock absorbing characteristics. Gap Pad® VO Ultra Soft is an electrically isolating material, which allows its use in applications requiring isolation between heat sinks and high-voltage, bare-leaded devices.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP PAD VO ULTRA SOFT			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Mauve/Pink	Mauve/Pink	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	_
Thickness (inch) / (mm)	0.020 to 0.250	0.508 to 6.350	ASTM D374
Inherent Surface Tack (1 sided)	I	I	_
Density (Bulk Rubber) (g/cc)	1.6	1.6	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness (Bulk Rubber) (Shore 00) (1)	5	5	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	8	55	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	6000	6000	ASTM D149
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150
Volume Resistivity (Ohm-meter)	1011	1011	ASTM D257
Flame Rating	V-0	V-0	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	1.0	1.0	ASTM D5470
THERMAL PERFORMANCE vs. STRAIN			
	Deflection (%	strain) 10	20 30
Thermal Impedance (°C-in²/W) 0.040" (3) 1.97 1.87 1.68			

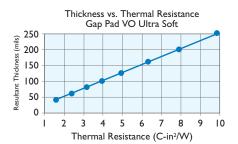
1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². 3) The ASTM DS470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

TYPICAL APPLICATIONS INCLUDE

- Telecommunications
- · Computer and peripherals
- Power conversion
- Between heat-generating semiconductors or magnetic components and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader

CONFIGURATIONS AVAILABLE

· Sheet form and die-cut parts



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Disclaimer

Note:

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Reference 0.1